

## **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **Listing of Claims:**

Claims 1 – 11 (Canceled).

Claim 12 (Withdrawn From Consideration): Semiconductor device manufacturing equipment comprising : a transfer chamber; a plurality of working chambers, a plurality of wafer support members disposed in each of said working chambers and configured to support a plurality of wafers side-by-side, each of said working chambers being respectively connected to said transfer chamber; and a robot disposed in said transfer chamber, said robot including a robot arm, the robot arm having a working range that encompasses said plurality of working chambers and comprising a branched wafer support arm having a plurality of wafer supports capable of simultaneously supporting a plurality of wafers, the number of said wafer supports of said robot arm corresponding to the number of wafer support members disposed in each of said chambers such that said robot can transfer a plurality of wafers at one time between respective ones of said working chambers via said transfer chamber.

Claim 13 (New): Semiconductor device manufacturing equipment comprising: A transfer chamber having a first side and a second side located directly across the interior of the transfer chamber from said first side; a plurality of load lock chambers

connected to said transfer chamber independently of each other at said first side of the transfer chamber, some of said loadlock chambers being disposed at a plurality of levels, respectively, at said first side of said transfer chamber, a number of said loadlock chambers being disposed side-by-side in a first axial direction on at least one of said levels, and each of said load lock chambers having first and second doors that separate the interior of the load lock chamber from the environment outside the equipment and the interior of said transfer chamber, respectively; a plurality of process chambers in which wafers are processed, said process chambers being connected to said transfer chamber independently of each other at said second side of said transfer chamber, each of said process chambers being disposed across said transfer chamber from a respective one of said loadlock chambers and vice versa, whereby some of said process chambers are disposed at said plurality of levels, respectively, at said second side of the transfer chamber, and a number of said loadlock chambers are disposed side-by-side in said first axial direction on said at least one of said levels; and a robot disposed in said transfer chamber, said robot comprising a robot arm, and a wafer support member disposed at a terminal end of said robot arm so as to move with said robot arm, said robot arm being supported so as to be independently linearly translatable in said first axial direction, linearly translatable in a vertical direction, and rotatable about a vertical axis, and said wafer support member being supported by said robot arm so as to be extendable and retractable independently of said robot arm at said terminal end of the robot arm,

wherein the robot has a working envelope that allows the wafer support to transfer wafers between any of said load lock chambers and the respective process chamber disposed across therefrom.